

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHUO-HSIU HSU	02/14/2017
RECEIVING PARTY DATA	
Name:	FOXCONN INTERCONNECT TECHNOLOGY LIMITED
Street Address:	Floor 4, Willow House, Cricket Square, P O Box 2804
City:	Grand Cayman
State/Country:	CAYMAN ISLANDS
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15438786
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	US59523
NAME OF SUBMITTER:	WEI TE CHUNG
SIGNATURE:	/WEI TE CHUNG/
DATE SIGNED:	02/22/2017
Total Attachments: 2	
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ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

- 1. SHUO-HSIU HSU , residing at New Taipei, Taiwan
- 2. _____ , residing at _____
- 3. _____ , residing at _____
- 4. _____ , residing at _____
- 5. _____ , residing at _____
- 6. _____ , residing at _____
- 7. _____ , residing at _____
- 8. _____ , residing at _____

hereby sell(s), assign(s) and transfer(s) unto: **FOXCONN INTERCONNECT TECHNOLOGY LIMITED** having a principal place of business at **Floor 4, Willow House, Cricket Square, P O Box 2804, Grand Cayman KY1-1112 , Cayman Islands**, hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **ELECTRICAL CONNECTOR ASSEMBLY AND MODULE SPACER THEREOF** for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____

[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	<u>Shuo-Hsiu Hsu</u> SHUO-HSIU HSU	<u>2/14/2017</u> Date
2.	_____	_____ Date
3.	_____	_____ Date
4.	_____	_____ Date
5.	_____	_____ Date
6.	_____	_____ Date
7.	_____	_____ Date
8.	_____	_____ Date
9.	_____	_____ Date